

IN THE CLAIMS:

Please amend Claims 1, 4 and 19 as follows.

1. (Amended) A method for forming a rough surface, comprising:
providing a substrate;

immersing a surface layer of said substrate in a solution
contained within a tank, said solution being able to remove said
surface layer;

A1 forming a plurality of bubbles in said solution, wherein part of
said bubbles are located on a surface of said surface layer, and
wherein said bubbles stay on said substrate due to no relative motion
between said tank and said substrate exists; and

removing said solution.

A2 4. (Amended) The method of claim 1, further comprises putting
said substrate in a reactor and immersing said substrate by said [high
pressure] solution, and then keep normal pressure of said reactor such
that said bubbles are formed in said solution.

19. (Amended) A method for forming a rough surface,
comprising:

A3 providing a substrate;

forming a plurality of bubbles in a solution, said solution being able to remove said surface layer;

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immersing a surface layer of said substrate in said solution contained with a tank, wherein part of said bubbles are located on a surface of said surface layer, wherein said bubbles stay on said substrate due to no relative motion between said tank and said substrate exists; and
removing said solution.

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Please add Claims 20-28 as follows.

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20. (Added) The method of claim 19, further comprises putting said solution in a reactor and reducing the pressure of said reactor such that said bubbles are formed in said solution before said substrate being immersed.

21. (Added) The method of claim 19, further comprises putting said substrate in a reactor and conveying a gas into said reactor such that said bubbles are formed in said solution before said substrate being immersed.

22. (Added) The method of claim 19, further comprises putting said substrate in a reactor and keeping normal pressure of said reactor

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such that said bubbles are formed in said solution before said substrate being immersed.

23. (Added) The method of claim 19, further comprising cover part of said surface by a photoresist before said substrate being immersed in said solution.

24. (Added) The method of claim 19, further comprising perform a dry process after said solution being removed.

25. (Added) The method of claim 19, wherein said solution is chosen from a group consisting of: hydrofluoric acid, nitric acid, mixture of hydrofluoric acid and nitric acid, hydrogen peroxide, ammonium fluoride, mixture of hydrogen peroxide and hydrofluoric acid, and mixture of ammonium fluoride and hydrofluoric acid.

26. (Added) The method of claim 19, wherein said surface layer is chosen from a group of: oxide layer, silicon layer, polysilicon layer, tungsten layer, tungsten silicide layer, titanium layer, titanium silicide layer, copper layer, photoresist, silicon nitride layer, and spin on glass.

27. (Added) A method for forming a rough surface, comprising:
providing a substrate, said substrate having a surface layer;
covering part of said surface layer by a photoresist;

immersing said surface layer and said photoresist in a solution contained with a tank, said solution being able to remove said surface layer;

forming a plurality of bubbles in said solution, wherein part of said bubbles are located on a surface of said surface layer, and wherein said bubbles stay in said substrate due to no relative motion between said tank and said substrate exists; and

removing said solution.

28. (Added) The method of claim 27, no relative motion between said solution and said substrate being existent after said surface layer being immersed.

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